



Material Content Data Sheet



Sales Product Name		TLE8386-2EL		Issued		28. August 2013		
MA#		MA001140392						
Package		PG-SSOP-14-3		Weight*		83.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.378	2.85	2.85	28520	28520
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8263	
wire	non noble metal	copper	7440-50-8	27.978	33.55	34.43	335522	344301
	noble metal	gold	7440-57-5	0.211	0.25	0.25	2526	2526
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1175
plastics		epoxy resin	-	4.509	5.41		54069	
	inorganic material	silicondioxide	60676-86-0	44.399	53.25	58.78	532460	587704
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11706	11706
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9206	9206
glue	plastics	epoxy resin	-	0.334	0.40		4009	
	noble metal	silver	7440-22-4	1.003	1.20	1.60	12028	16037
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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